

# 40V, 190A, 2.1mΩ N-channel Power Trench MOSFET

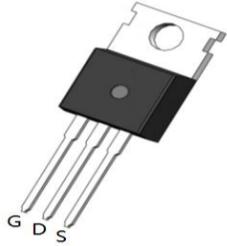
## JMTC025N04D

Features	Product Summary		
• Excellent $R_{DS(ON)}$ and Low Gate Charge	Parameters	Value	Unit
• 100% UIS TESTED	$V_{DSS}$	40	V
• 100% $\Delta V_{ds}$ TESTED	$V_{GS(th)}_{Typ}$	2.7	V
• Halogen-free; RoHS-compliant	$I_D(@V_{GS}=10V)$	190	A
	$R_{DS(ON)}_{Typ}(@V_{GS}=10V)$	2.1	mΩ

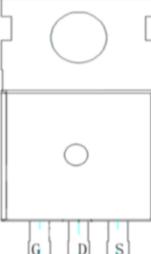
**Applications**

- Load Switch
- PWM Application
- Power Management

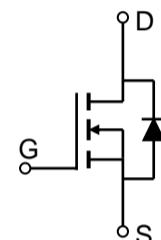




**TO-220-3L Top View**



**Pin Assignment**



**Schematic**

### Ordering Information

Device	Marking	MSL	Form	Package	Tube(pcs)	Per Carton (pcs)
JMTC025N04D	JMTC025N04D	N/A	Tape&Reel	TO-220-3L	50	5000

### Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-to-Source Voltage	40	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 25$	V
$I_D$	Continuous Drain Current <small>(<math>T_C = 25^\circ\text{C}</math>)</small>	190	A
		134	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	Refer to Fig.4	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	711	mJ
$P_D$	Power Dissipation <small>(<math>T_C = 25^\circ\text{C}</math>)</small>	309	W
		123	
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	50	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.4	

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	40	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.9	2.7	4.0	V
$R_{\text{DS(ON)}}$	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 10\text{V}, I_D = 30\text{A}$	-	2.1	2.6	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$R_g$	Gate Resistance	$f = 1\text{MHz}$	-	1.0	-	$\Omega$
$C_{\text{iss}}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 20\text{V}, f = 1\text{MHz}$	-	9516	-	pF
$C_{\text{oss}}$	Output Capacitance		-	962	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	570	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 20\text{V}, I_D = 30\text{A}$	-	147	-	nC
$Q_{\text{gs}}$	Gate Source Charge		-	50	-	nC
$Q_{\text{gd}}$	Gate Drain("Miller") Charge		-	31	-	nC
<b>Switching Characteristics</b>						
$t_{d(\text{on})}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 20\text{V}$ $I_D = 30\text{A}, R_{\text{GEN}} = 2.7\Omega$	-	26	-	ns
$t_r$	Turn-On Rise Time		-	30	-	ns
$t_{d(\text{off})}$	Turn-Off DelayTime		-	59	-	ns
$t_f$	Turn-Off Fall Time		-	19	-	ns
<b>Body Diode Characteristics</b>						
$I_S$	Maximum Continuous Body Diode Forward Current	-	-	190	-	A
$I_{\text{SM}}$	Maximum Pulsed Body Diode Forward Current	-	-	760	-	A
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 30\text{A}$	-		1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F = 30\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	33	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	29	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2.  $E_{AS}$  condition: Starting  $T_J=25^\circ\text{C}$ ,  $V_{DD}=20\text{V}$ ,  $V_G=10\text{V}$ ,  $R_G=25\text{ohm}$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=53.34\text{A}$ ,  $V_{DD}=0\text{V}$  during time in avalanche.

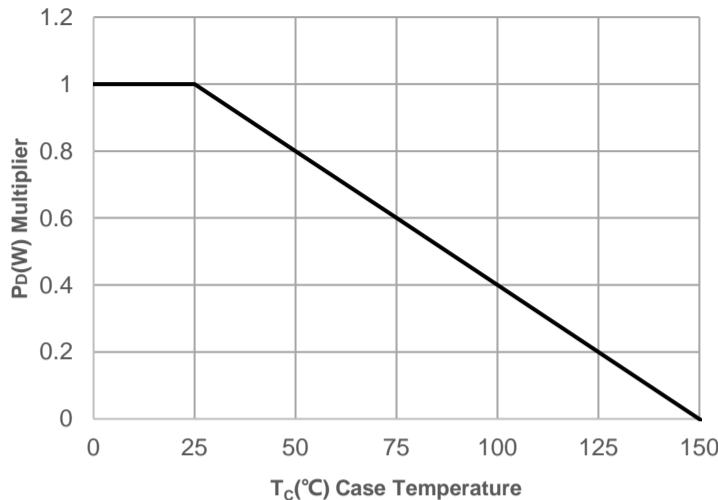
3.  $R_{\theta JA}$  is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB.

4. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

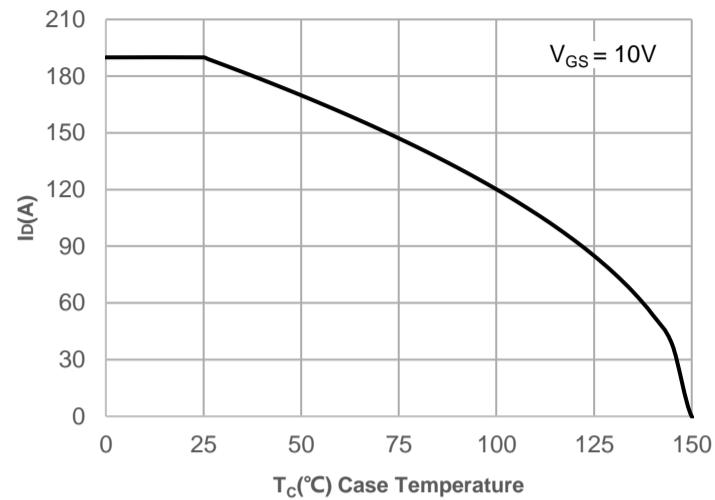


## Typical Performance Characteristics

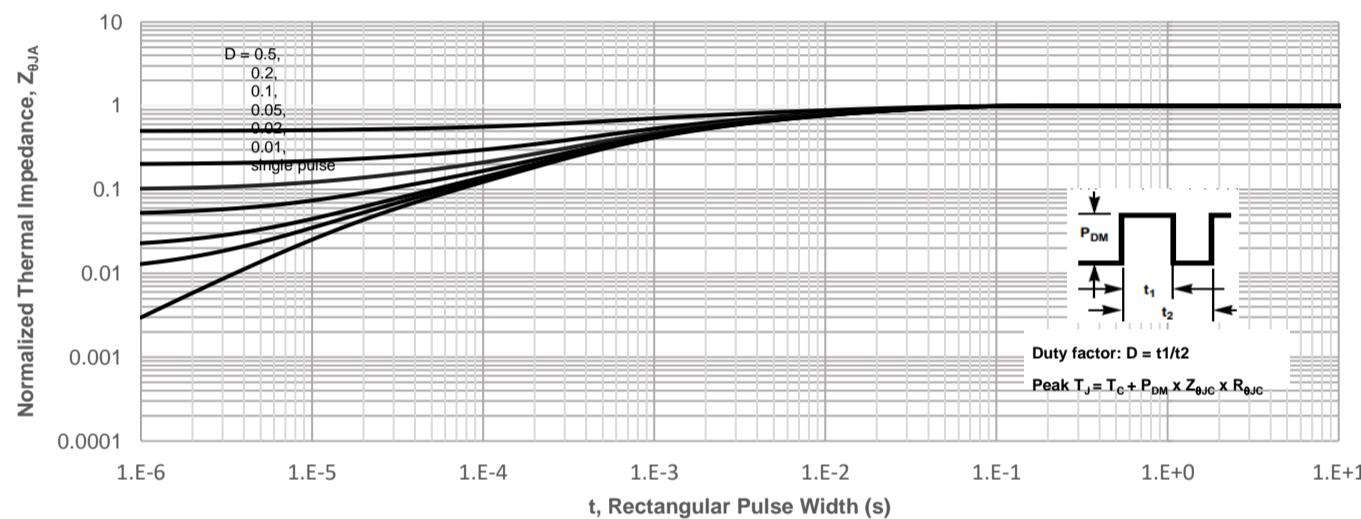
**Figure 1: Power De-rating**



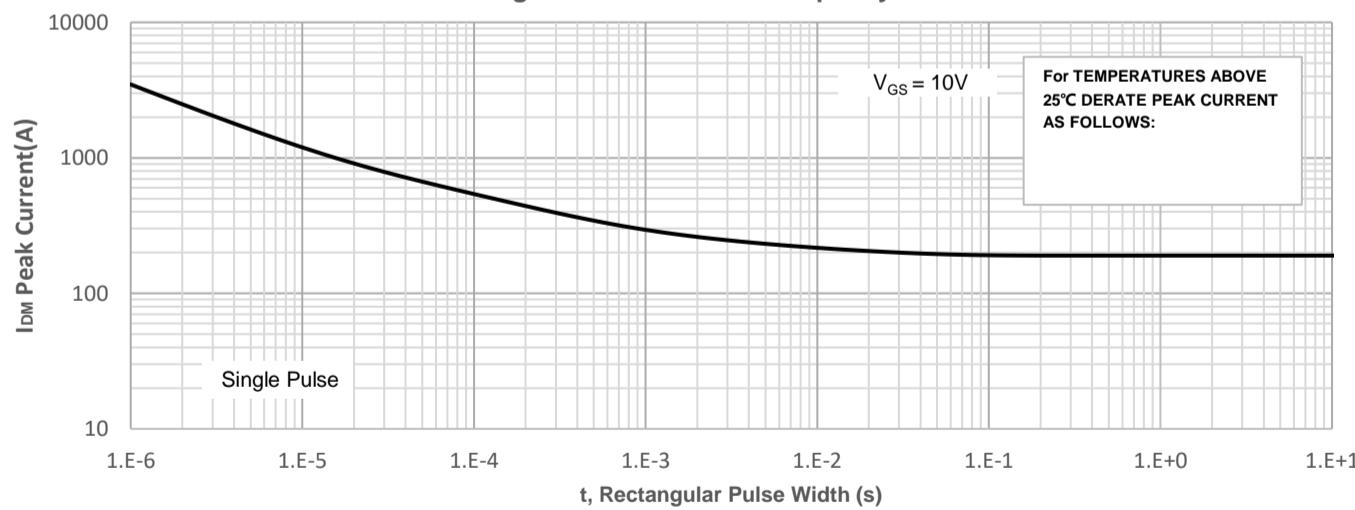
**Figure 2: Current De-rating**



**Figure 3: Normalized Maximum Transient Thermal Impedance**

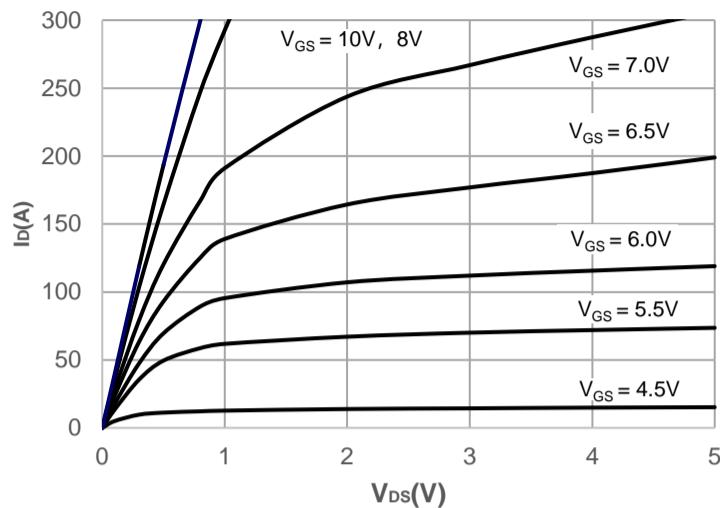


**Figure 4: Peak Current Capacity**

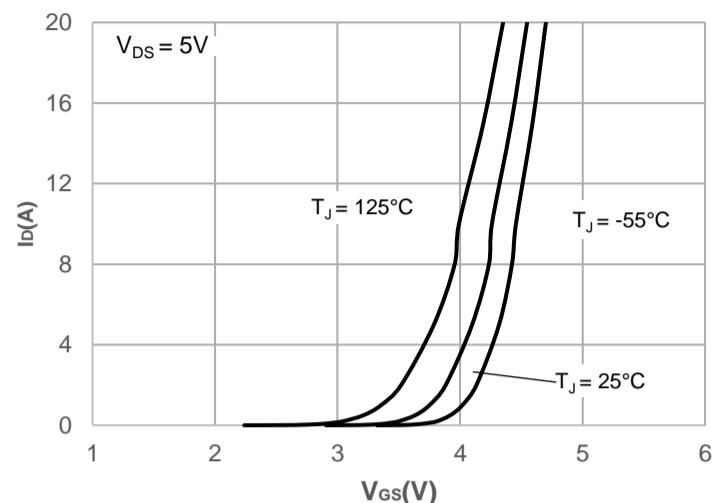


## Typical Performance Characteristics

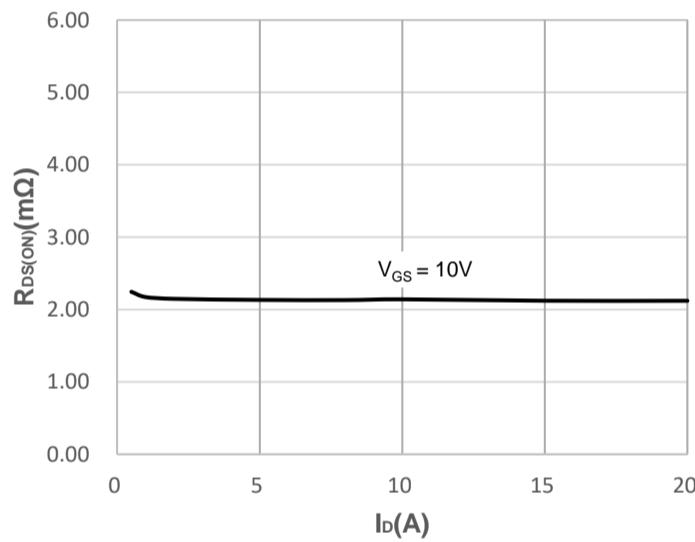
**Figure 5: Output Characteristics**



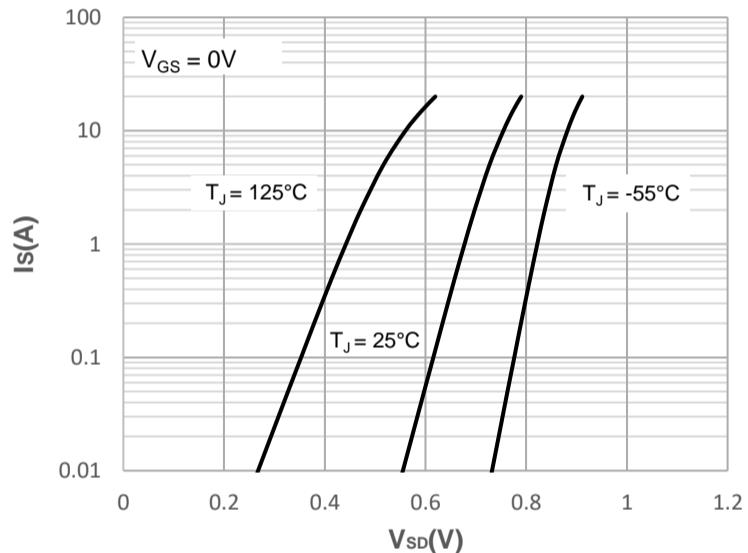
**Figure 6: Typical Transfer Characteristics**



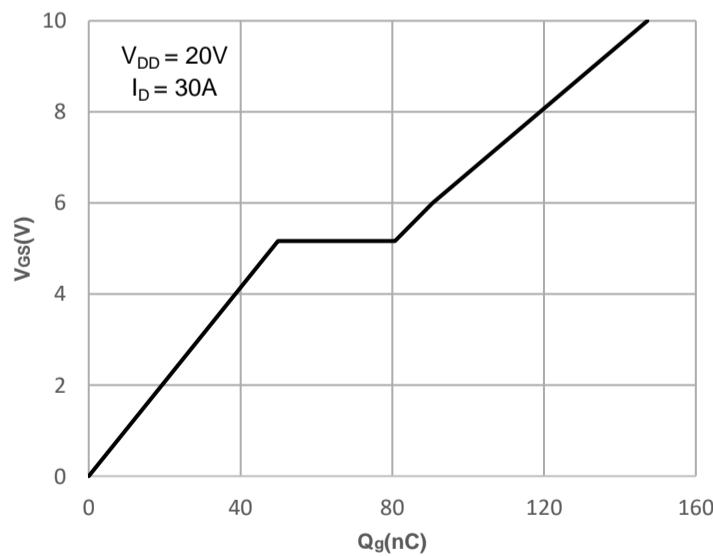
**Figure 7: On-resistance vs. Drain Current**



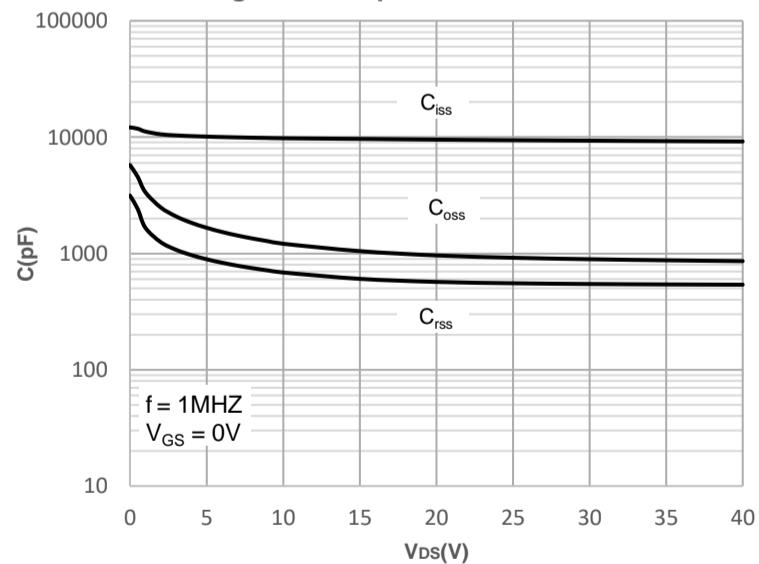
**Figure 8: Body Diode Characteristics**



**Figure 9: Gate Charge Characteristics**

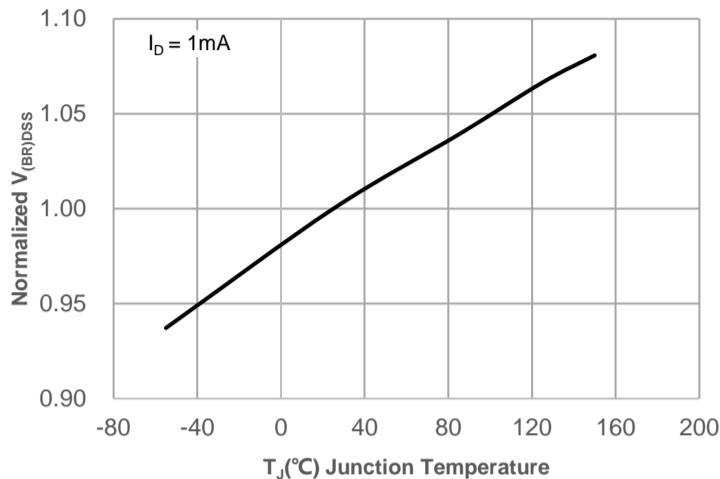


**Figure 10: Capacitance Characteristics**

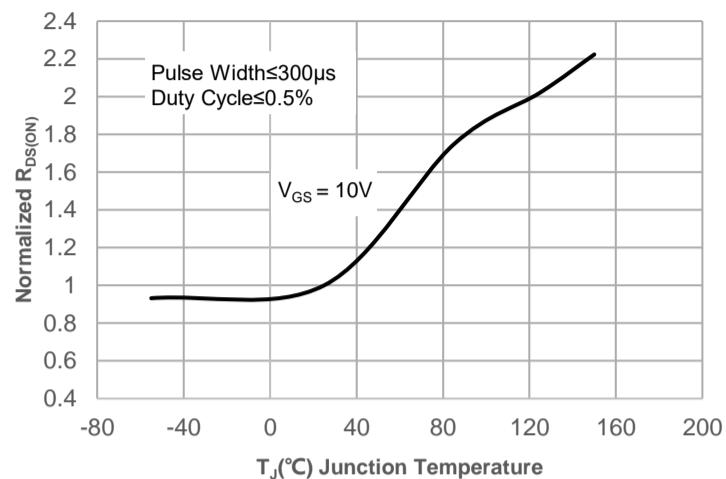


## Typical Performance Characteristics

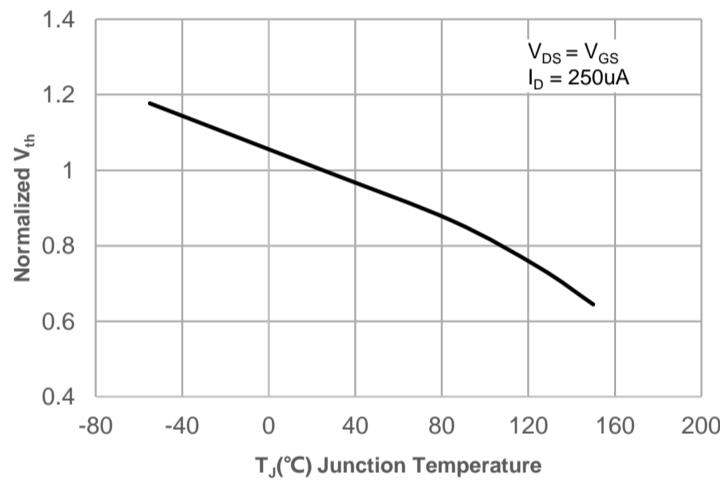
**Figure 11: Normalized Breakdown voltage vs. Junction Temperature**



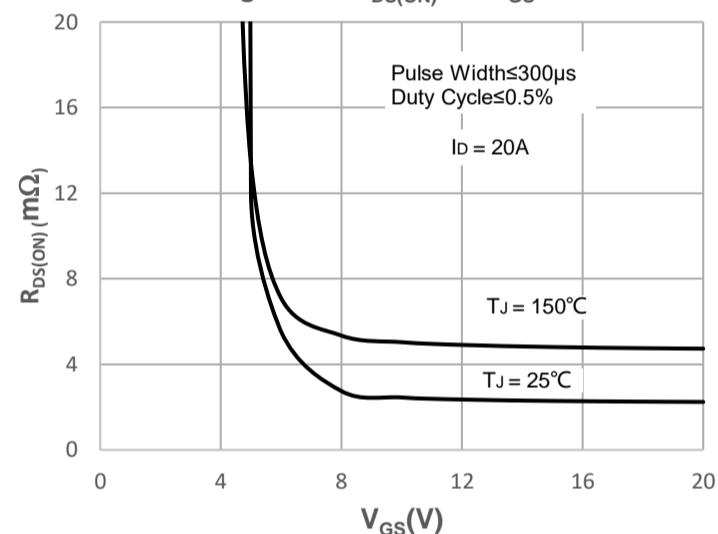
**Figure 12: Normalized on Resistance vs. Junction Temperature**



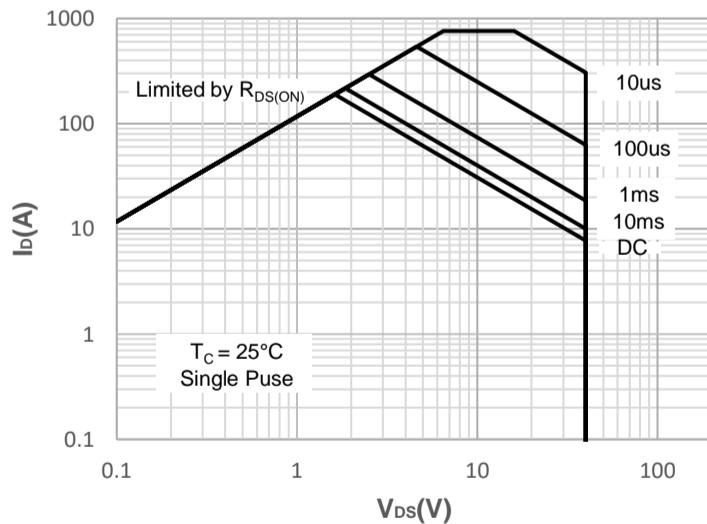
**Figure 13: Normalized Threshold Voltage vs. Junction Temperature**



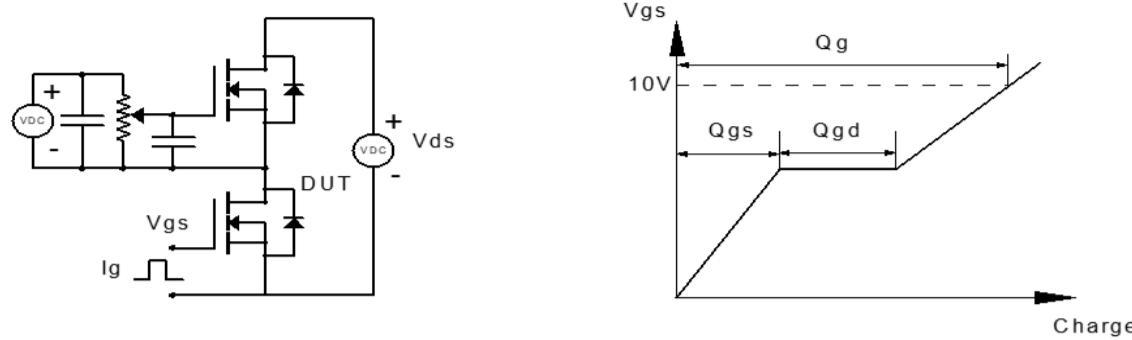
**Figure 14:  $R_{DS(ON)}$  vs.  $V_{GS}$**



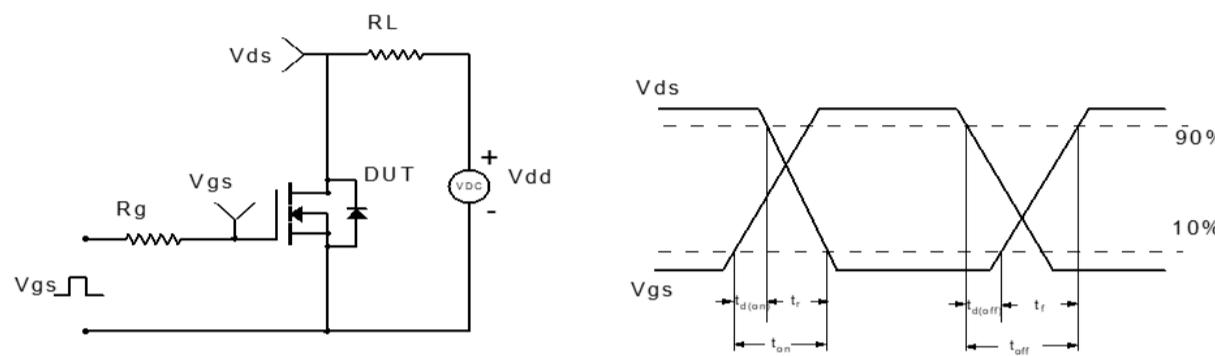
**Figure 15: Maximum Safe Operating Area**



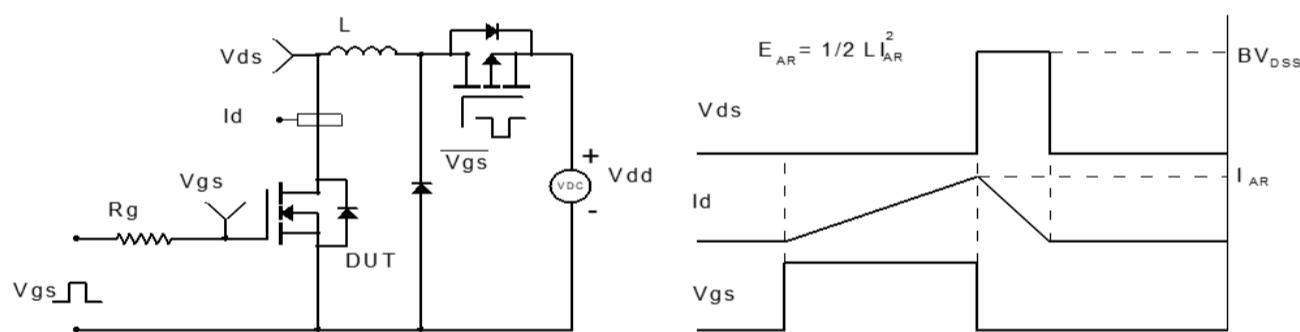
## Test Circuit



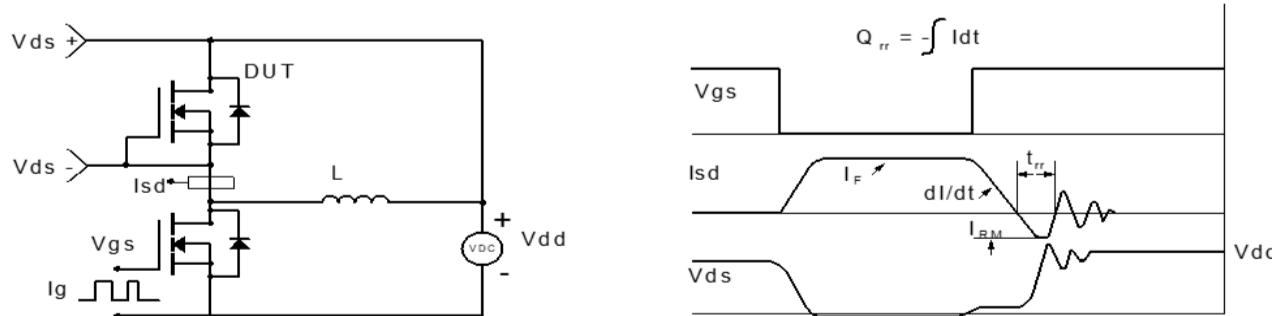
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**



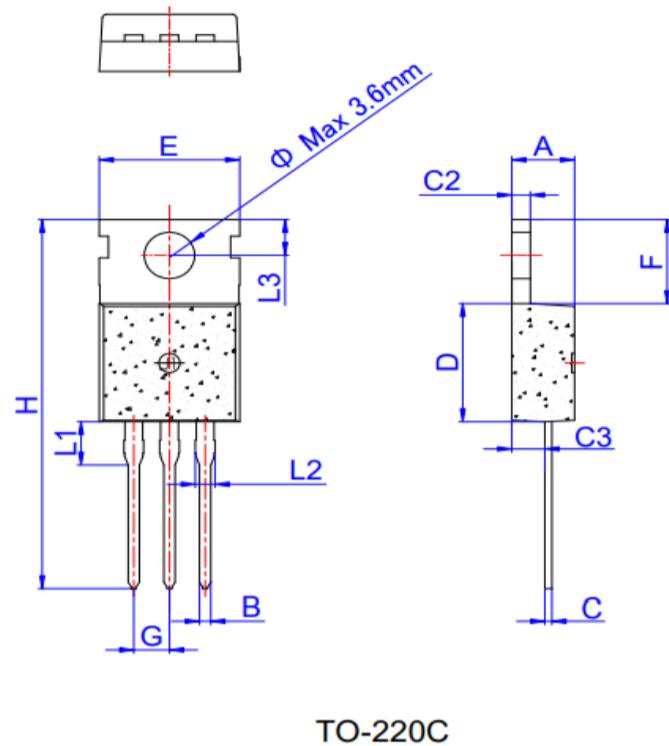
**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**



## Package Mechanical Data(TO-220-3L)



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	0.70		0.90	0.028		0.035
C	0.45		0.60	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.20		2.60	0.087		0.102
D	8.90		9.90	0.350		0.390
E	9.90		10.3	0.390		0.406
F	6.30		6.90	0.248		0.272
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.39			0.133	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

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